



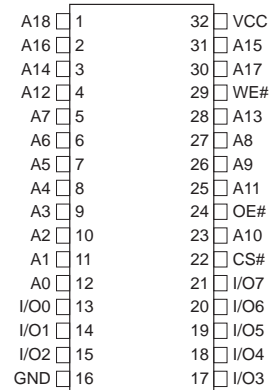
# 512Kx8, MONOLITHIC SRAM, SMD 5962-95613

## FEATURES

- Access Times 70, 85, 100, 120ns
- MIL-STD-883 Compliant Devices Available
- Evolutionary, Corner Power/Ground Pinout JEDEC Approved
  - 32 pin Ceramic DIP (Package 300)
  - 32 lead Ceramic SOJ (Package 101)
- Commercial, Industrial and Military Temperature Ranges
- 5V Power Supply
- Low Power CMOS
- Low Power Data Retention
- TTL Compatible Inputs and Outputs

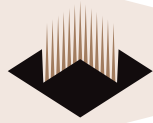
## EVOLUTIONARY PINOUT

32 DIP  
32 CSOJ (DE)  
TOP VIEW



## PIN DESCRIPTION

A0-18	Address Inputs
I/O0-7	Data Input/Output
CS#	Chip Select
OE#	Output Enable
WE#	Write Enable
VCC	+5.0V Power
GND	Ground



**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T <sub>A</sub>	-55	+125	°C
Storage Temperature	T <sub>STG</sub>	-65	+150	°C
Signal Voltage Relative to GND	V <sub>G</sub>	-0.5	V <sub>CC</sub> +0.5	V
Junction Temperature	T <sub>J</sub>		150	°C
Supply Voltage	V <sub>CC</sub>	-0.5	7.0	V

**RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V <sub>CC</sub>	4.5	5.5	V
Input High Voltage	V <sub>IH</sub>	2.2	V <sub>CC</sub> + 0.3	V
Input Low Voltage	V <sub>IL</sub>	-0.3	+0.8	V
Operating Temp. (Mil.)	T <sub>A</sub>	-55	+125	°C

**TRUTH TABLE**

CS#	OE#	WE#	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	X	L	Write	Data In	Active
L	H	H	Out Disable	High Z	Active

**CAPACITANCE**

(T<sub>A</sub> = +25°C)

Parameter	Symbol	Condition	Max	Unit
Input capacitance	C <sub>IN</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	12	pF
Output capacitance	C <sub>OUT</sub>	V <sub>OUT</sub> = 0V, f = 1.0MHz	12	pF

*This parameter is guaranteed by design but not tested.*

**DC CHARACTERISTICS**

(V<sub>CC</sub> = 5.0V, GND = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	Conditions	Units	
			Min	Max
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5, V <sub>IN</sub> = GND to V <sub>CC</sub>	10	µA
Output Leakage Current	I <sub>LO</sub>	CS# = V <sub>IH</sub> , OE# = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>	10	µA
Operating Supply Current	I <sub>CC</sub>	CS# = V <sub>IL</sub> , OE# = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5	50	mA
Standby Current	I <sub>SB</sub>	CS# = V <sub>IH</sub> , OE# = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5	1	mA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.1mA, V <sub>CC</sub> = 4.5	0.4	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -1.0mA, V <sub>CC</sub> = 4.5	2.4	V

NOTE: DC test conditions: V<sub>IH</sub> = V<sub>CC</sub> - 0.3V, V<sub>IL</sub> = 0.3V

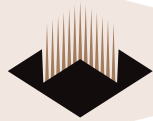
**DATA RETENTION CHARACTERISTICS**

(T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	Conditions	Military			Units
			Min	Typ	Max	
Data Retention Supply Voltage	VDR	CS# ≥ V <sub>CC</sub> - 0.2V	2.0		5.5	V
Data Retention Current	I <sub>CCDR1</sub>	V <sub>CC</sub> = 3V		100	400	µA

**DATA RETENTION CHARACTERISTICS FOR LOW POWER “L” VERSION**

Parameter	Symbol	Conditions	Min	Max	Units
Data Retention Supply Voltage	VDR	CS# ≥ V <sub>CC</sub> - 0.2V	2.0	5.5	V
Low Power Data Retention (L)	I <sub>CCDR1</sub>	V <sub>CC</sub> = 2V		185	µA



**AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, GND = 0V, T<sub>A</sub> = -55°C to +125°C)

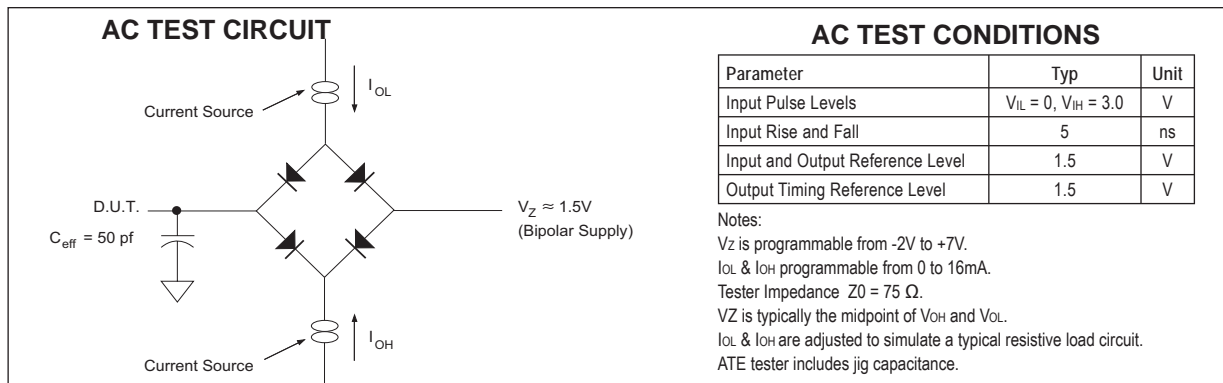
Parameter	Symbol	-70		-85		-100		-120		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle										
Read Cycle Time	t <sub>RC</sub>	70		85		100		120		ns
Address Access Time	t <sub>AA</sub>		70		85		100		120	ns
Output Hold from Address Change	t <sub>OH</sub>	5		5		5		5		ns
Chip Select Access Time	t <sub>ACS</sub>		70		85		100		120	ns
Output Enable to Output Valid	t <sub>OE</sub>		35		40		50		60	ns
Chip Select to Output in Low Z	t <sub>CLZ</sub> <sup>1</sup>	10		10		10		10		ns
Output Enable to Output in Low Z	t <sub>OLZ</sub> <sup>1</sup>	5		5		5		5		ns
Chip Disable to Output in High Z	t <sub>CHZ</sub> <sup>1</sup>		25		25		35		35	ns
Output Disable to Output in High Z	t <sub>OHZ</sub> <sup>1</sup>		25		25		35		35	ns

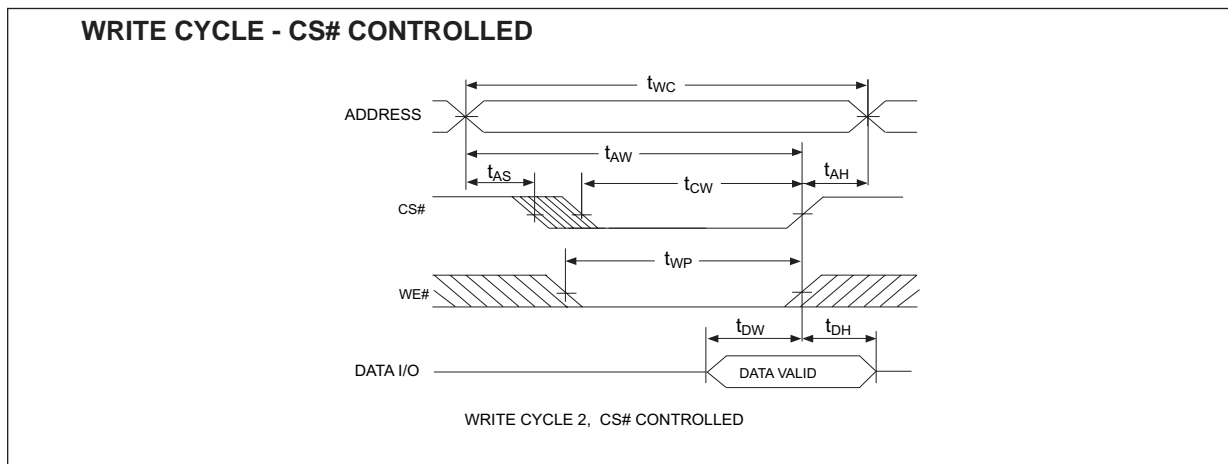
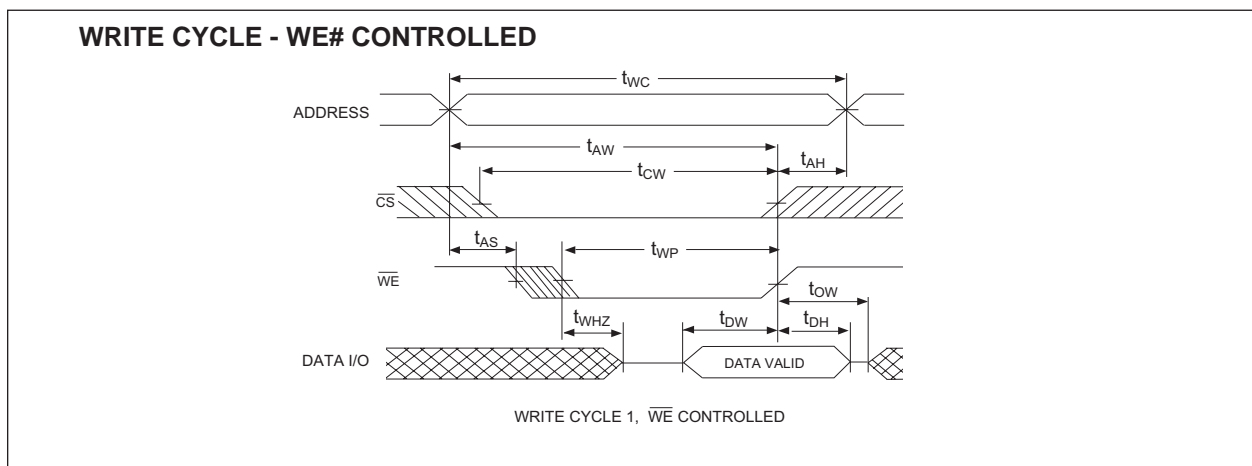
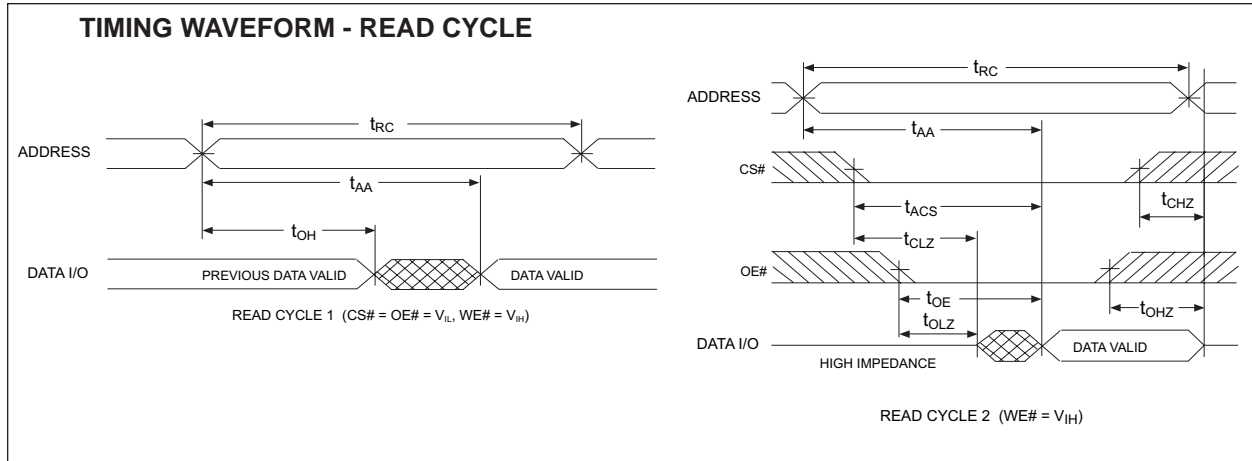
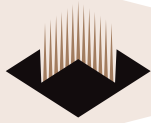
1. This parameter is guaranteed by design but not tested.

**AC CHARACTERISTICS**  
(V<sub>CC</sub> = 5.0V, GND = 0V, T<sub>A</sub> = -55°C to +125°C)

Parameter	Symbol	-70		-85		-100		-120		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle										
Write Cycle Time	t <sub>WC</sub>	70		85		100		120		ns
Chip Select to End of Write	t <sub>CW</sub>	60		75		80		100		ns
Address Valid to End of Write	t <sub>AW</sub>	60		75		80		100		ns
Data Valid to End of Write	t <sub>DW</sub>	30		30		40		40		ns
Write Pulse Width	t <sub>WP</sub>	50		50		60		60		ns
Address Setup Time	t <sub>AS</sub>	0		0		0		0		ns
Address Hold Time	t <sub>AH</sub>	5		5		5		5		ns
Output Active from End of Write	t <sub>OW</sub> <sup>1</sup>	5		5		5		5		ns
Write Enable to Output in High Z	t <sub>WHZ</sub> <sup>1</sup>		25		25		35		35	ns
Data Hold from Write Time	t <sub>DH</sub>	0		0		0		0		ns

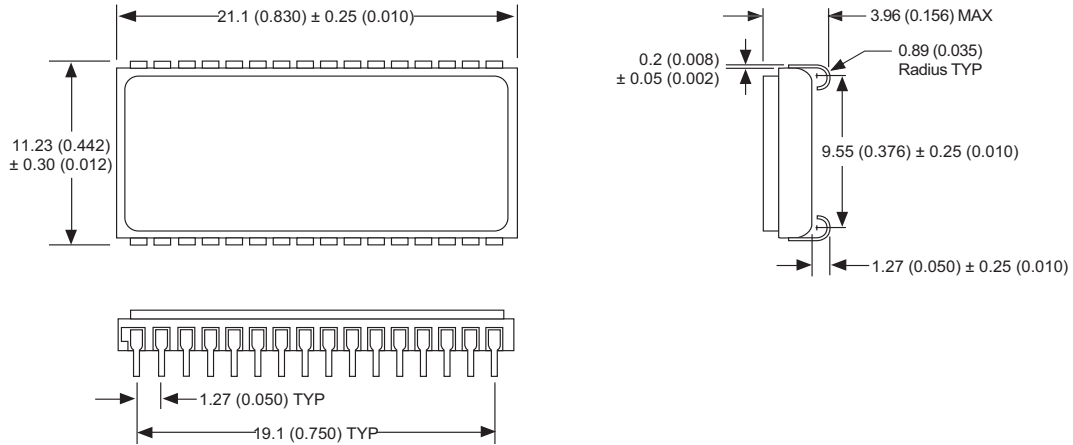
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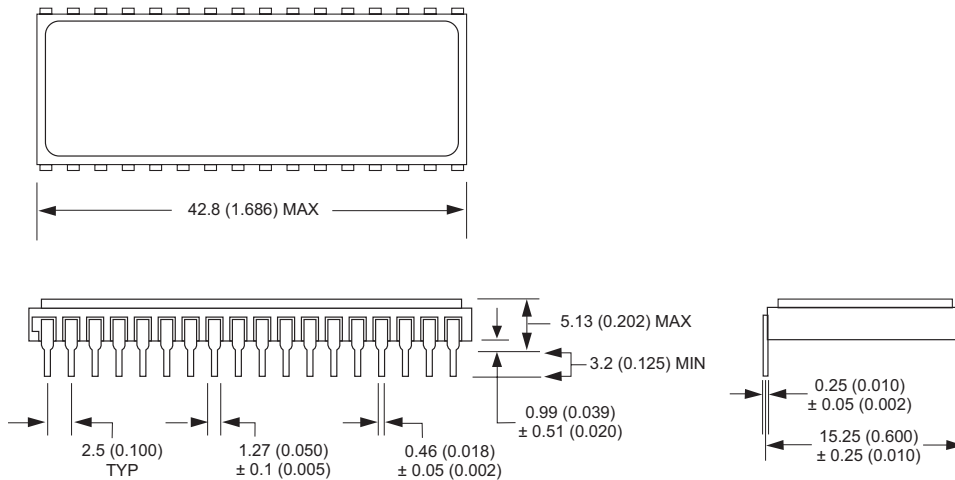


**PACKAGE 101: 32 LEAD, CERAMIC SOJ**



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

**PACKAGE 300: 32 PIN, CERAMIC DIP, SINGLE CAVITY SIDE BRAZED**

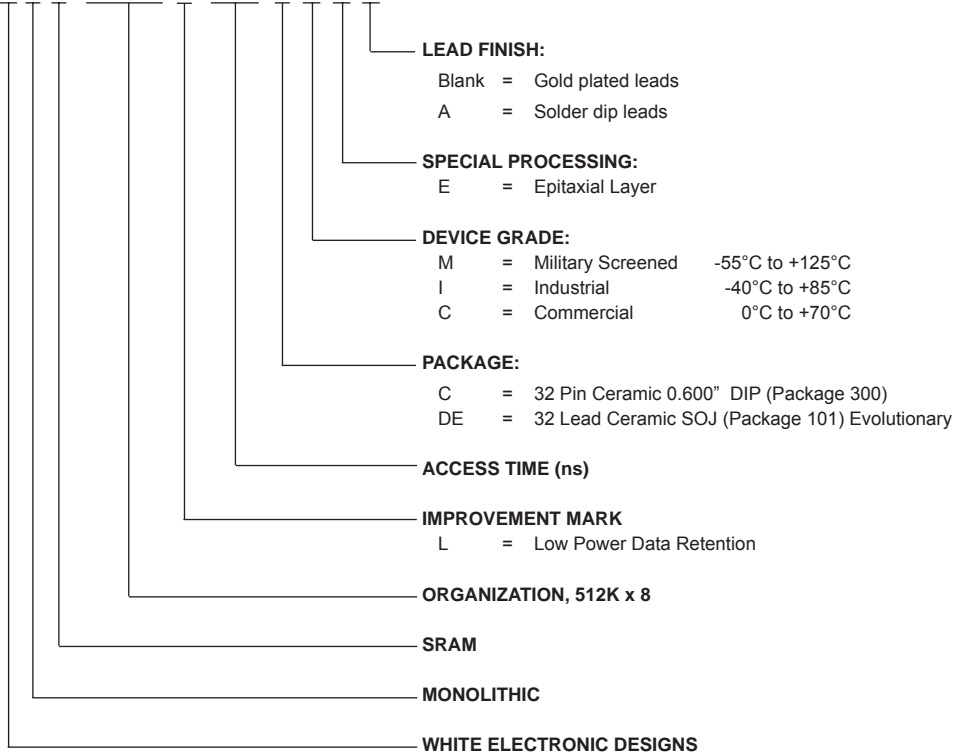


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**ORDERING INFORMATION**

**W M S 512K 8 L - XXX X X X X**



DEVICE TYPE	SPEED	PACKAGE	SMD NO.
512K x 8 SRAM Monolithic	120ns	32 pin DIP (C)	5962-95613 01HYX
512K x 8 SRAM Monolithic	100ns	32 pin DIP (C)	5962-95613 02HYX
512K x 8 SRAM Monolithic	85ns	32 pin DIP (C)	5962-95613 03HYX
512K x 8 SRAM Monolithic	70ns	32 pin DIP (C)	5962-95613 04HYX
512K x 8 SRAM Monolithic	120ns	32 lead SOJ Evol (DE)	5962-95613 01HTX
512K x 8 SRAM Monolithic	100ns	32 lead SOJ Evol (DE)	5962-95613 02HTX
512K x 8 SRAM Monolithic	85ns	32 lead SOJ Evol (DE)	5962-95613 03HTX
512K x 8 SRAM Monolithic	70ns	32 lead SOJ Evol (DE)	5962-95613 04HTX